

Development of SiC sensors for harsh environment applications

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Silicon Carbide (SiC)

Material properties and benefits

- Wide band gap material
- Low leakage current even after irradiation
- High breakdown voltage
- Possibility to work at room temperature after irradiation
- High saturation velocity
 - Potential for timing applications

Properties	Si	4H-SiC
Crystal Structure	Diamond	Hexagonal
Energy Gap : E_G (eV)	1.12	3.26
Electron Mobility : μ_n (cm^2/Vs)	1400	900
Hole Mobility : μ_p (cm^2/Vs)	600	100
Breakdown Field : E_B (V/cm) X10 ⁶	0.3	3
Thermal Conductivity (W/cm°C)	1.5	4.9
Saturation Drift Velocity : v_s (cm/s) X10 ⁷	1	2.7
Relative Dielectric Constant : ϵ_s	11.8	9.7

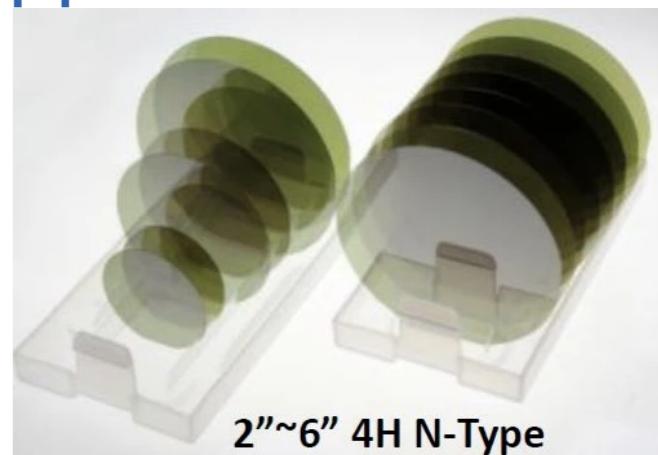
ROHM, SiC Power Devices White Paper



Potential for fabrication of 3D detectors
and other MEMS structures.

Current status of SiC technology

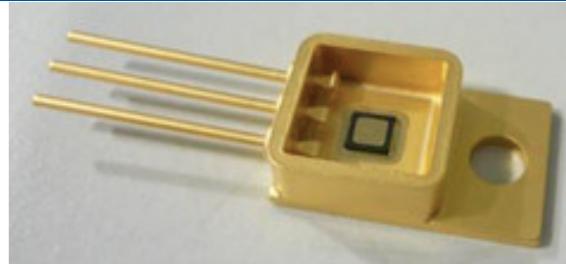
- SiC technology is fully developed for commercial applications
 - High quality 4- and 6-inch SiC wafers available
 - Sought after for power electronics
 - Diodes have been successfully developed



CNM, ALTER, Universitat de València

BepiColombo space mission

- Protection diodes for solar arrays
- Working temperature range -170°C to 300°C
 - Stable with thermal cycling
- High reliability and radiation hard

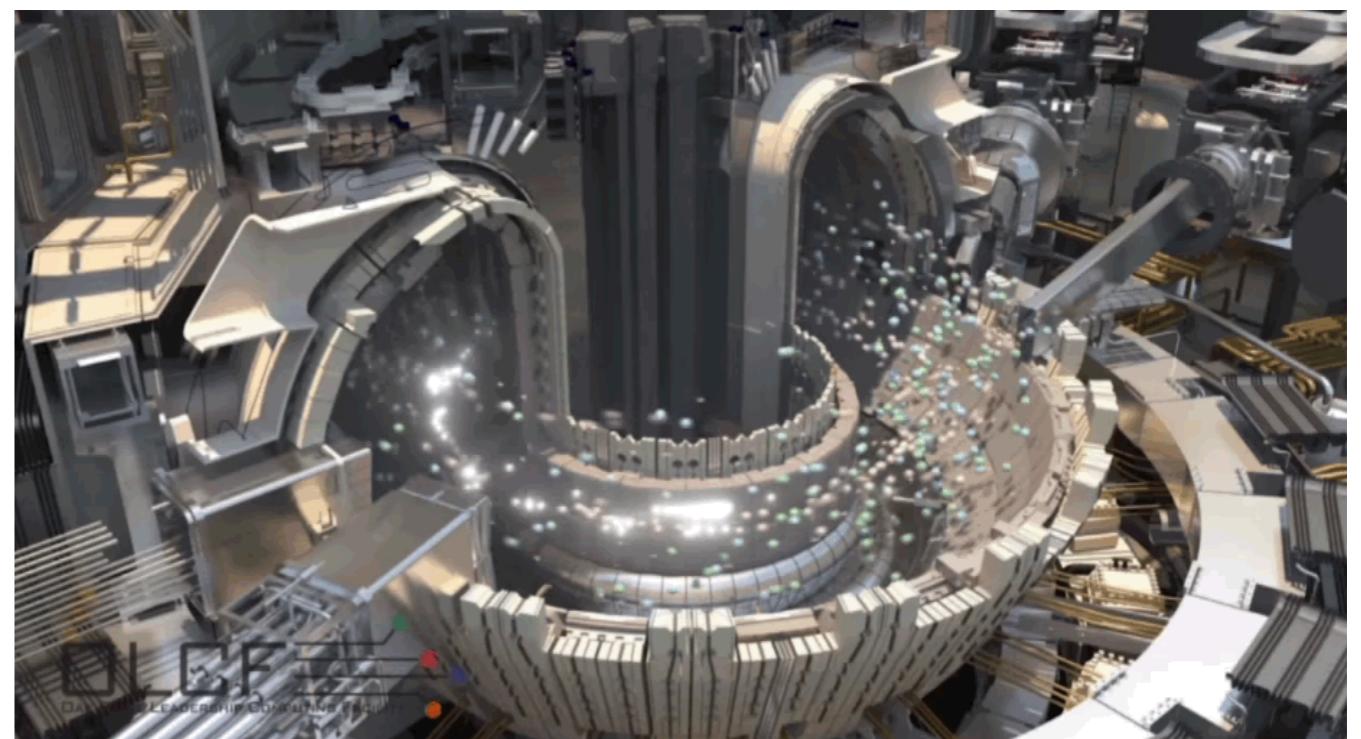


P. Godignon et al., ISPSD Hiroshima, 2010, pp. 351-354

Main potential applications

Nuclear fusion reactors

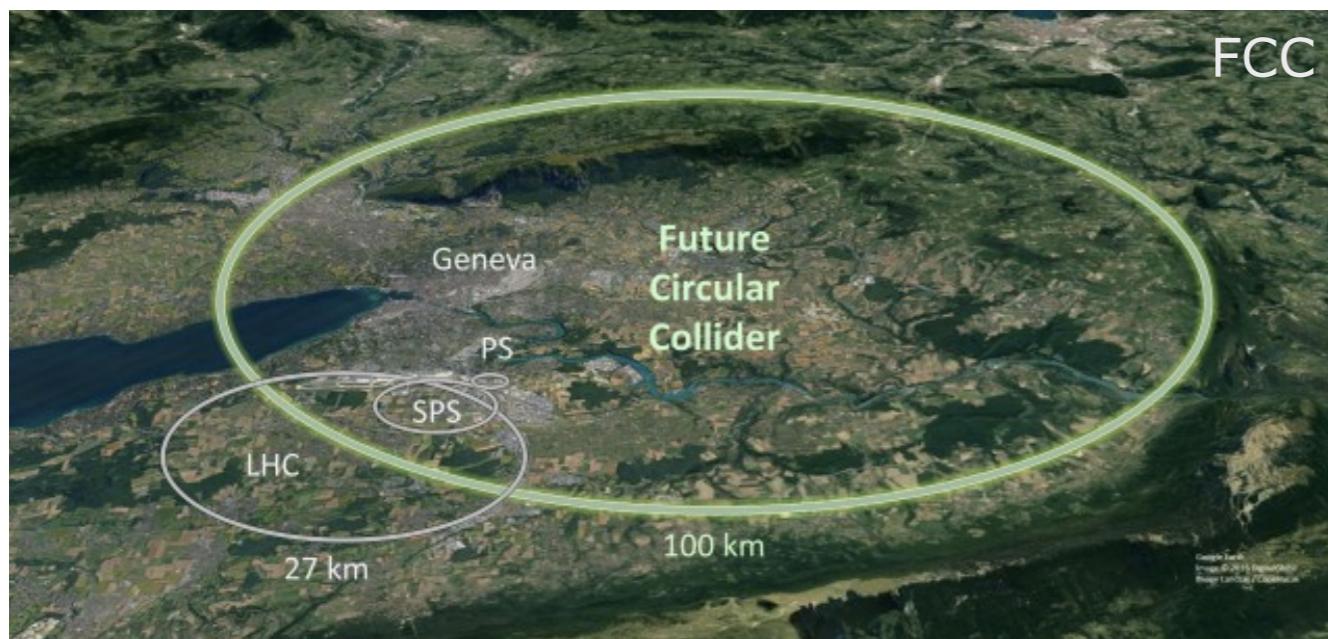
- Neutron diagnostics.



Aerospace

- Sensors and electronics.

Main potential applications



High energy physics

- Sensors for large colliders

Planar Devices

GRACE Project

Graphene-enhanced Radiation detector on Silicon Carbide for harsh Environments



Unión Europea

Fondo Europeo
de Desarrollo Regional
“Una manera de hacer Europa”

Project funding reference: RTC-2017-6369-3

Institutes and people involved

ALTER

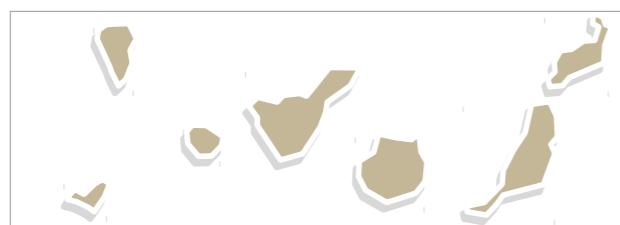
- J. Moreno
- D. López
- E. Cordero

CNA-CSIC

- M. C. Jiménez Ramos
- J. García López

CNM-IMB-CSIC

- G. Pellegrini
- G. Rius Suñé
- P. Godignon
- S. Otero Ugobono



GRACE Project

Graphene-enhanced Radiation detector on Silicon Carbide for harsh Environments

Main target applications:

- Plasma diagnosis in fusion reactors (e.g. ITER)
- Monitoring and control of high-temperature-operation components in spacecrafts

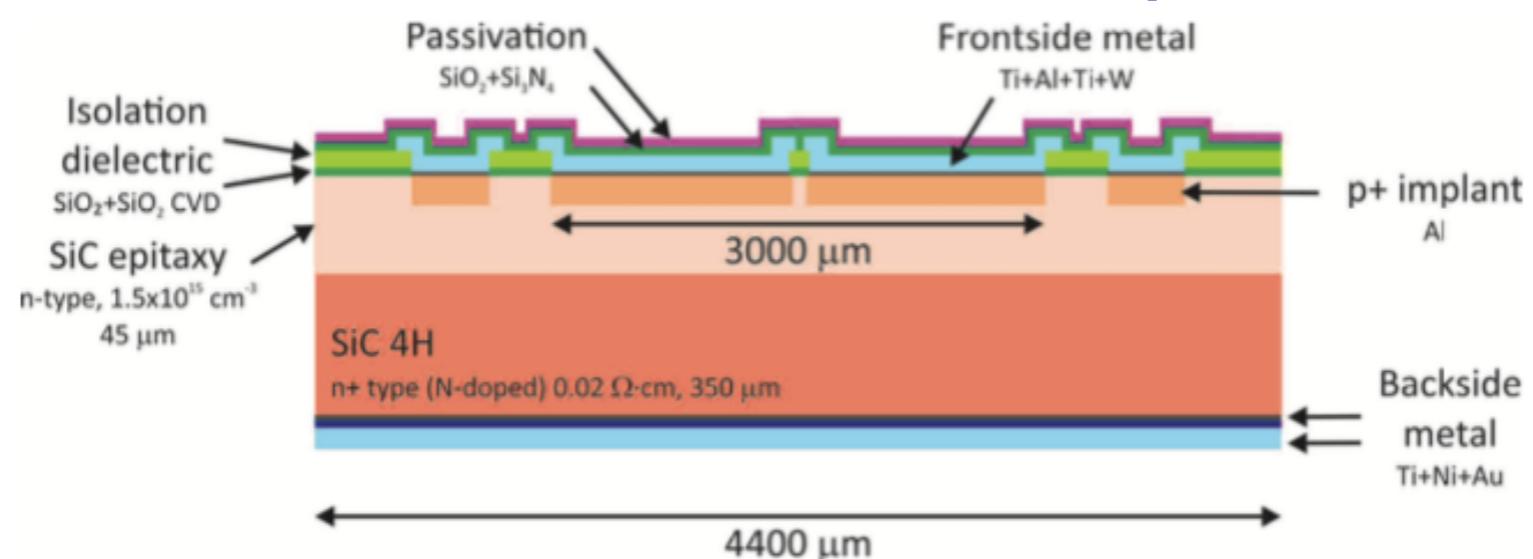
GRACE Project

Graphene-enhanced Radiation detector on Silicon Carbide for harsh Environments

Devices tolerant to

- **High radiation levels:** neutrons, protons, heavy ions, α-, and β-particles.
- **High temperatures:** at least [200°C, 500°C].

Cross section of a *conventional* 4-quadrant SiC sensor



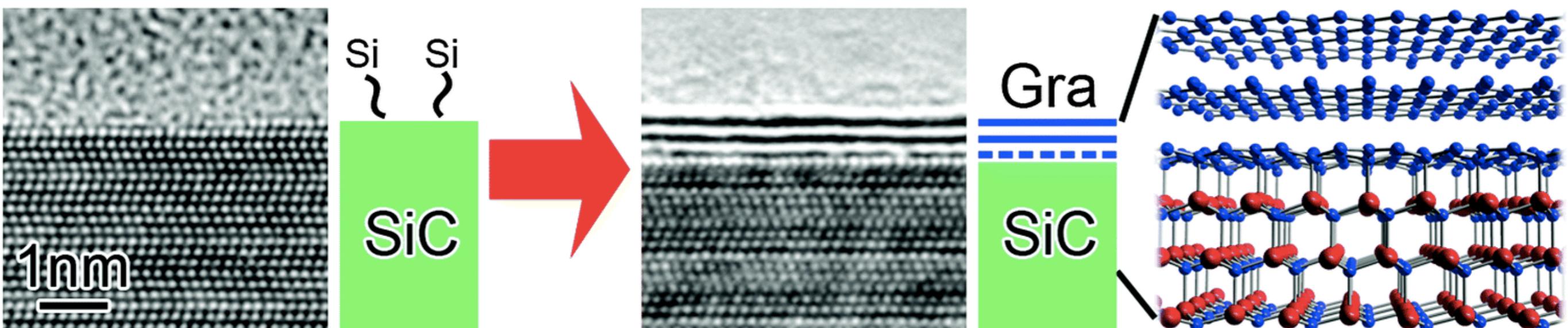
Graphene-enhancement

- Graphene layer between SiC surface and metallisation
- The metallisation may be removed altogether
 - Useful for heavy-ion detection
- Graphene could potentially improve
 - SiC-metal electrical contact
 - Thermal management

Epitaxial graphene technology

Graphenisation: epitaxial growth of graphene layers

- Thermal decomposition of SiC surfaces
 - Selective sublimation of atomic silicon
 - C atoms rearrange into a honeycomb structure



W. Norimatsu et al., Phys. Chem. Chem. Phys. 2014, 16, 3501-3511

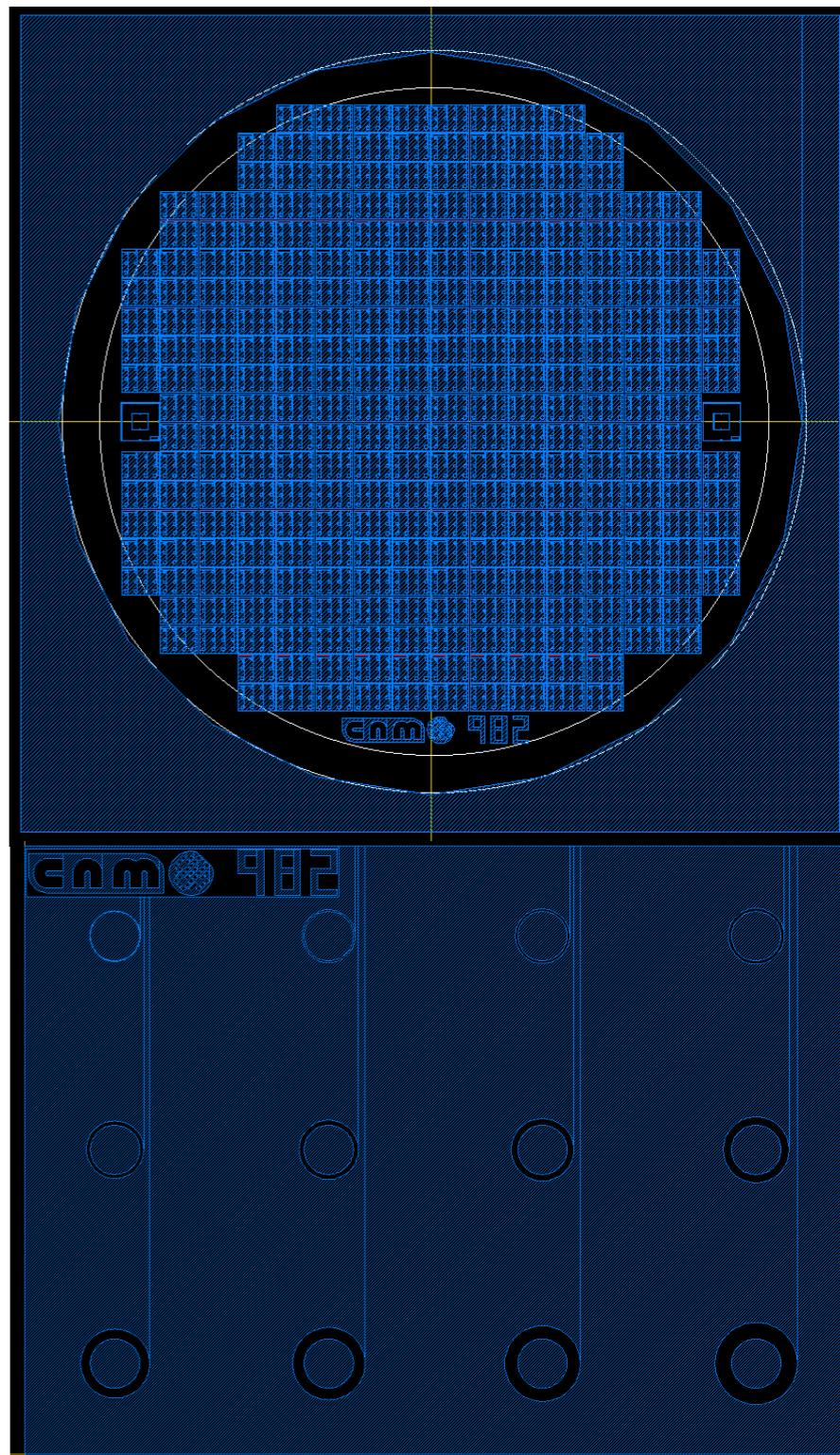
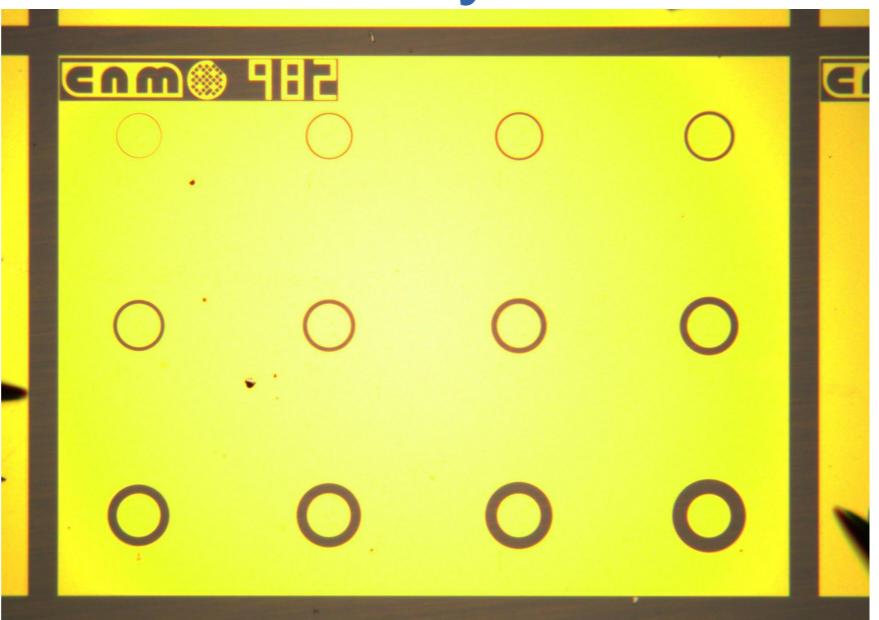
G. Rius, P. Godignon, Epitaxial Graphene on Silicon Carbide: Modelling, Devices, and Applications, Pan Stanford Pte. Ltd. (2018)

Graphenisation a.k.a. graphitisation

Current work plan at CNM

Optimisation of various contact configurations

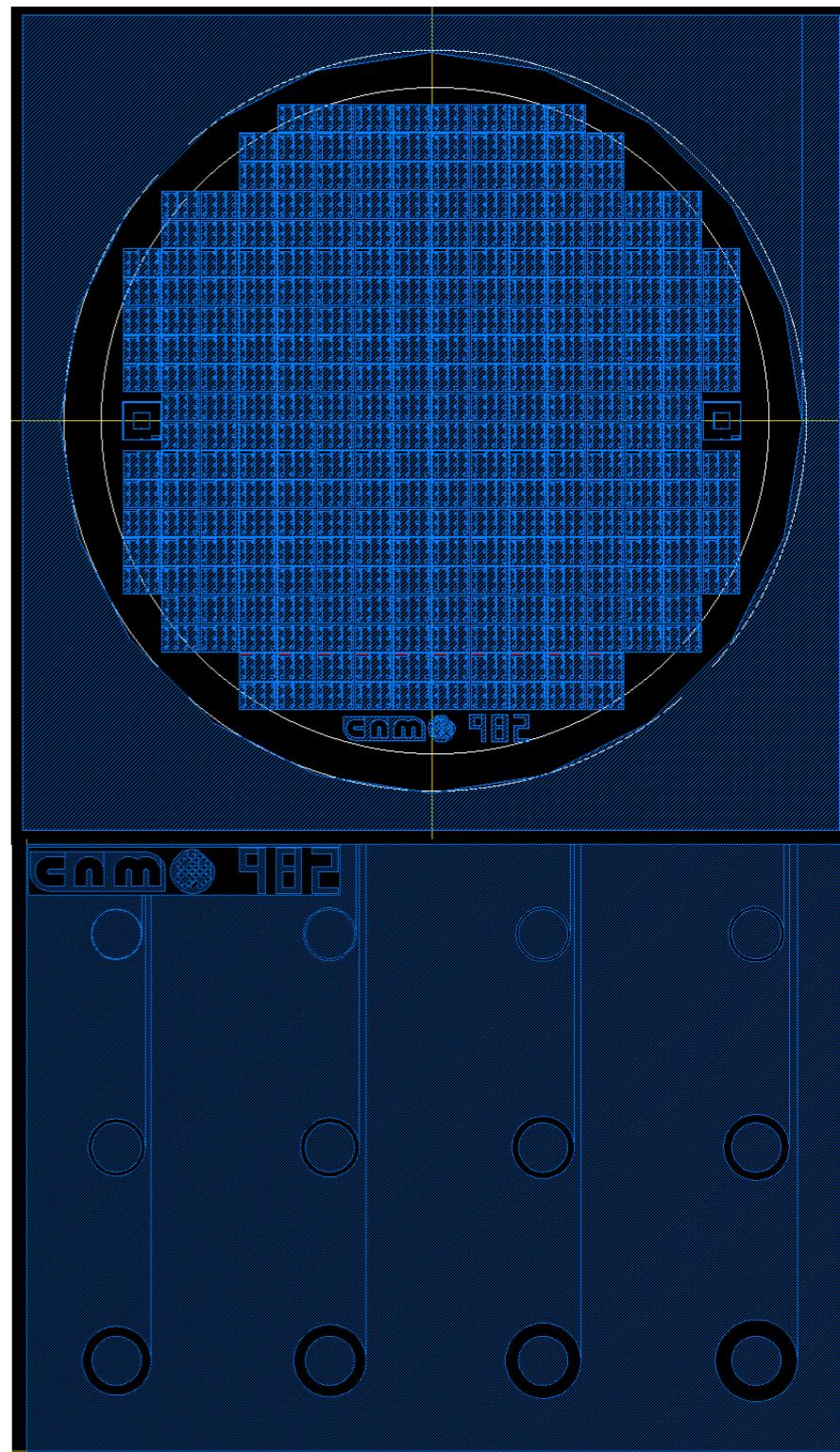
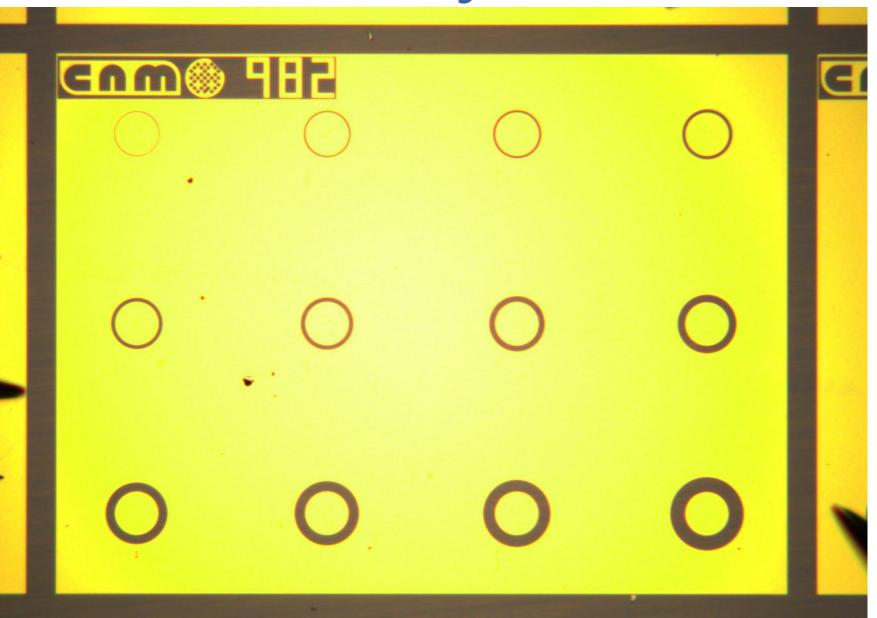
- Contact, and sheet resistivity study
- Testing of different metal combinations
- Effect of graphene in overall conductivity
- Radiation hardness
- Tolerance to high temperatures
- Wire-bond reliability



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Future work

- **Design and development of sensor prototypes**
- **Full characterisation to determine sensor viability:**
 - electrical properties
 - charge collection efficiency
 - tolerance to high temperatures
 - tolerance to temperature fluctuations (thermal cycle tests)
 - endurance limit (mechanical stress)
- **Irradiation campaigns**
- **Package design and development**
- **Device simulation**

3D Devices

RD50 Project on SiC

**Proof of concept of 3D detectors fabricated in
Silicon Carbide (SiC) semiconductor layers**

- **Explore an innovative method to produce 3D SiC sensors:**
 - Doping-selective electrochemical etching.



Project funding reference: RD50-2019-02

Institutes and people involved

JSI

- G. Kramberger

PSI

- M. Camarda
- M. Carulla Areste

CNM

- G. Pellegrini
- G. Rius Suñé
- P. Godignon
- J.M. Rafí Tatjer
- S. Otero Ugobono

IFAE

- S. Grinstein

IFCA

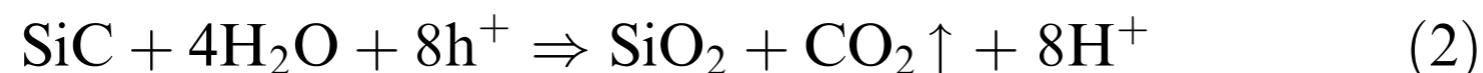
- I. Vila Álvarez



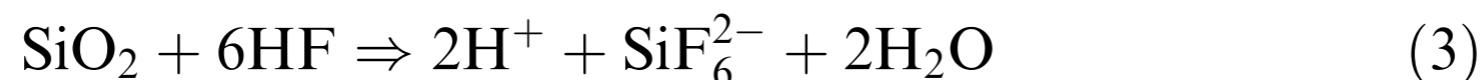
Doping-selective electrochemical etching

Basic etching mechanism:

- Carried out in an electrochemical cell
- The SiC is dipped in a solution of HF
- An electrical current is applied to the SiC
- Two-step process:
 - Oxidation of the SiC (current + electrolyte solution)



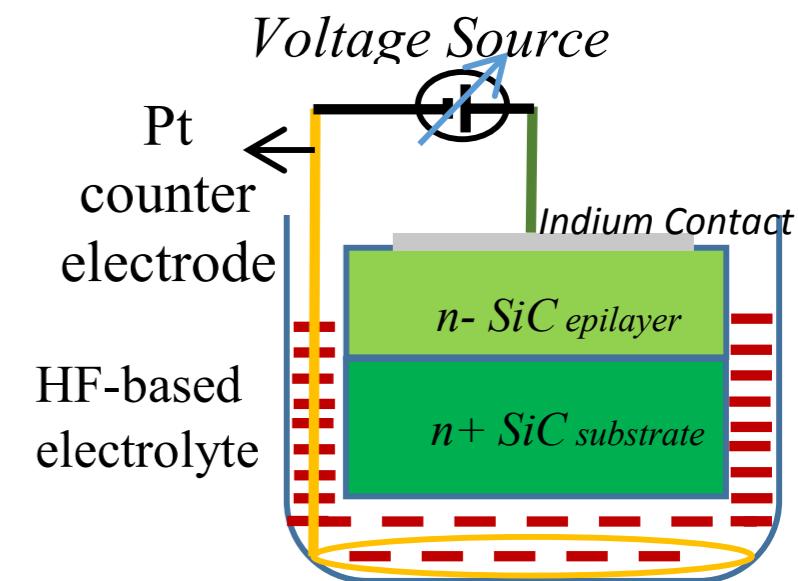
- Oxide is removed by HF (electrolyte solution)



S. Nida et al., J. Synchrotron Rad. (2019) 26, 28-35

S. Rysy et al., J Solid State Electrochem (1999) 3: 437-445

R. Dahal et al., Materials Science Forum (2017), 897, 379–382

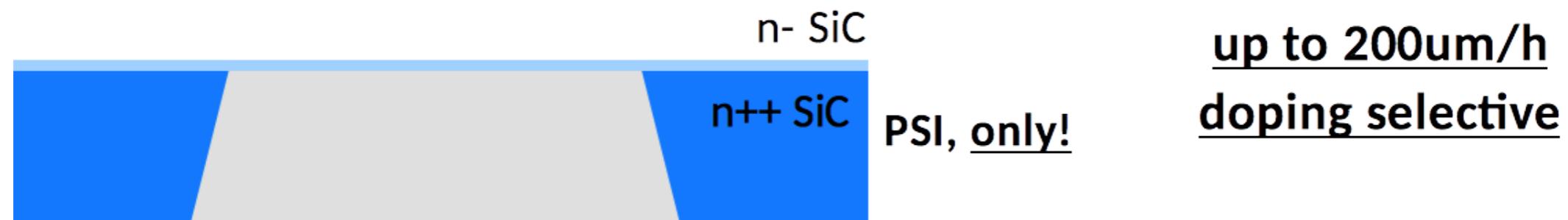


HF: hydrogen fluoride

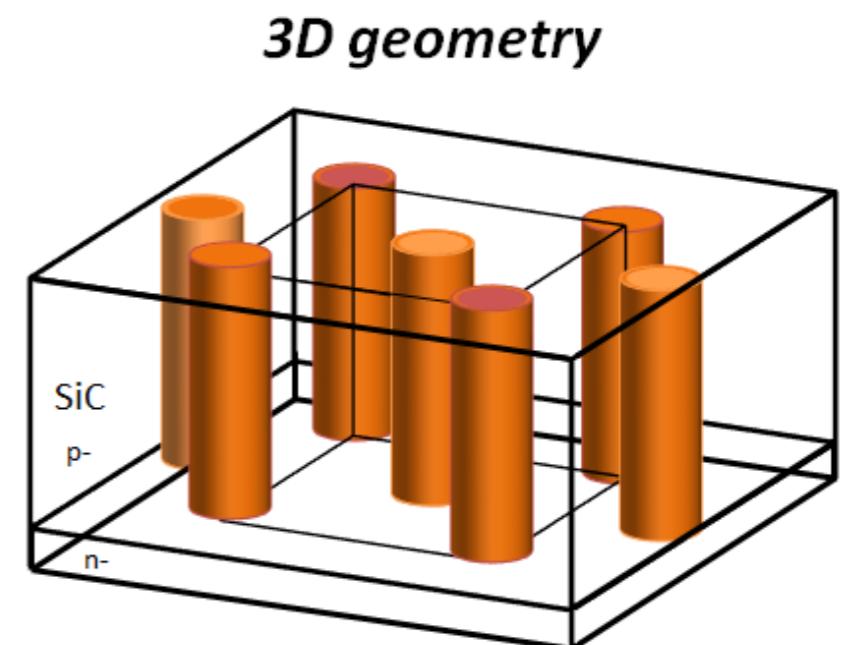
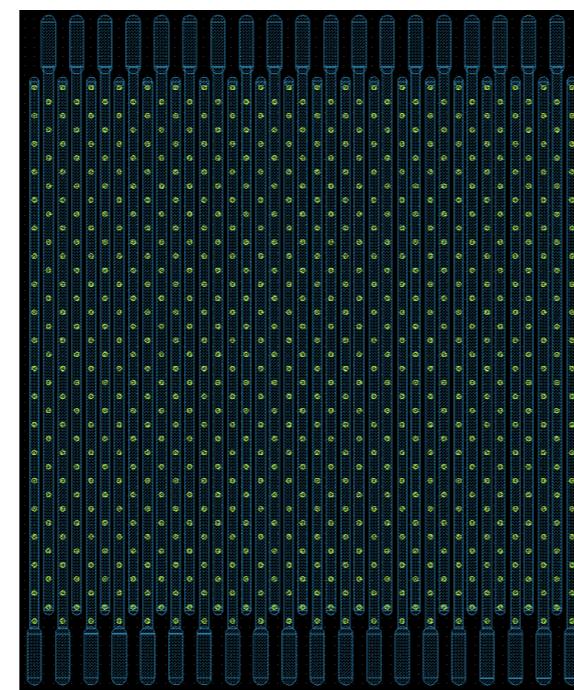
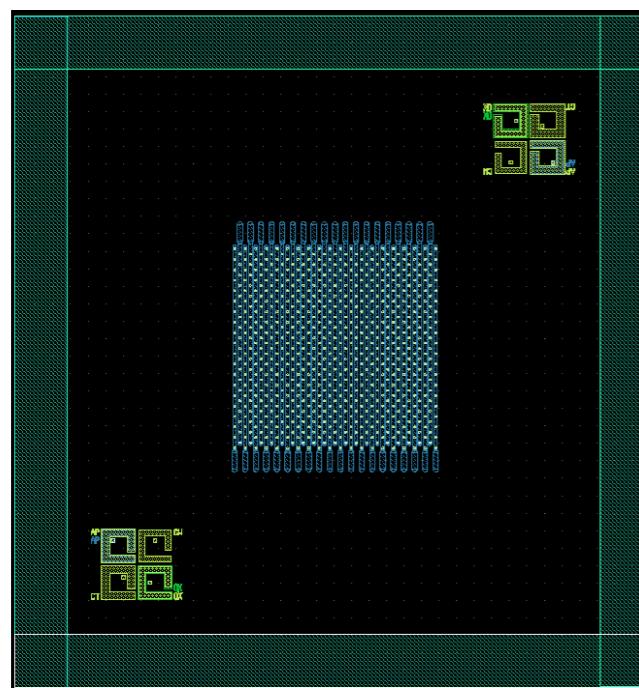
Doping-selective electrochemical etching

Process already applied for thin epitaxial membrane fabrication

- Electrochemical etching of highly doped 4H-SiC substrate



- Adaptation and optimisation of the etching process for production of columnar electrodes



Work plan

- **Explore the feasibility of the fabrication process**
- **Creation of Schottky contacts** inside the columns through metal sputtering
- **Irradiation campaigns and full characterisation:**
 - Electrical tests (CV/IV)
 - TPA and blue-laser TCT
 - Timing tests

Summary

- **SiC technology already fully developed for commercial applications**
- **CNM is developing innovative SiC sensors for harsh-environment applications**
- Architectures under study: **planar and 3D**
- Work under way on both projects

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- Architectures under study: **planar and 3D**
- Work under way on both projects
- **Looking for collaborators for defect studies**
- **Interested in this technology for your experiment?**



**Thank you very much
for your attention**